Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™)
SCDB Series

Push-in push-out mechanism applicable for three types of media.

Features
- Push-in push-out eject mechanism used for all three types of cards.
- Contact points are well protected to minimize the damage to a card for insertion and ejection.
- Available for reflow soldering.

Applications
- Personal digital assistant, personal computers, digital cameras, digital camcorders, etc.
- Home audio and visual equipment (TV, set top box, etc.)

Typical Specifications

<table>
<thead>
<tr>
<th>Items</th>
<th>Specifications</th>
</tr>
</thead>
<tbody>
<tr>
<td>Applicable media</td>
<td>SD Memory Card, MultiMediaCard™, Memory Stick™</td>
</tr>
<tr>
<td>Mounting method</td>
<td>Surface mounting type</td>
</tr>
<tr>
<td>Mounting system</td>
<td>Standard mount / Reverse mount</td>
</tr>
<tr>
<td>Media ejection structure</td>
<td>Push-push type</td>
</tr>
<tr>
<td>Operating temperature range</td>
<td>−25°C to +60°C</td>
</tr>
<tr>
<td>Voltage proof</td>
<td>500V AC 1minute</td>
</tr>
<tr>
<td>Insulation resistance(Initial)</td>
<td>1,000MΩ  min.</td>
</tr>
<tr>
<td>Contact resistance(Initial)</td>
<td>100mΩ  max.</td>
</tr>
<tr>
<td>Mating and unmating cycle</td>
<td>10,000 cycles (SD Memory Card, Memory Stick™)</td>
</tr>
</tbody>
</table>

Products List

<table>
<thead>
<tr>
<th>Media ejection structure</th>
<th>Mounting system</th>
<th>Feature</th>
<th>Stand-off (mm)</th>
<th>Product No.</th>
<th>Packing system</th>
<th>Drawing No.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Push-push type</td>
<td>Standard mount</td>
<td>With frame legs</td>
<td>0</td>
<td>SCDB1A0102</td>
<td>Tray</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Without frame legs</td>
<td></td>
<td>SCDB1C0101</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>Reverse mount</td>
<td>With boss</td>
<td></td>
<td>SCDB2A0101</td>
<td></td>
<td>3</td>
</tr>
</tbody>
</table>
## Dimensions

**Standard mount**

<table>
<thead>
<tr>
<th>No.</th>
<th>Style</th>
<th>PC board mounting dimensions (Viewed from the mounting face side)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>With frame legs</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Without frame legs</td>
<td></td>
</tr>
</tbody>
</table>

### With frame legs

- **No. 1**: Card eject stroke
- **No. 2**: Card lock position
- **No. 3**: Card center
- **No. 4**: Connector center

### Without frame legs

- **No. 2**: Card eject stroke
- **No. 3**: Card lock position
- **No. 4**: Connector center
- **No. 5**: Card center

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**Unit**: mm

- **Dimensions**
- **No.**
- **Style**
- **PC board mounting dimensions**
Dimensions

Reverse mount

<table>
<thead>
<tr>
<th>No.</th>
<th>Style</th>
</tr>
</thead>
</table>

PC board mounting dimensions (Viewed from the mounting face side)

Unit: mm

Connector for SD Memory Card
Connector for TransFlash™ Card
Connector for miniSD™ Card
Connector for RS-MMC™
Connector for Memory Stick™
Combine Type Connectors
Connector for Compact Flash™ Card
IC Card Connectors
PC Card Connectors
Connector for CMOS Camera Module
Soldering Conditions

Example of Reflow Soldering Condition (Reference)
2. Temperature measurement: Thermocouple 0.1 to 0.2 °CA (K) or CC (°T).
3. Temperature profile (Surface of products)

![Temperature Profile Graph]

- Room temperature
- 100°C
- 200°C
- 230°C (min.)
- 240°C (max.)
- 150°C
- 180°C
- Pre-heating 90±30 sec.
- Heating Time 10 sec. (max.)
- Time (s)

Cautions
1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.
5. This product has been designed and manufactured for applications to ordinary electronic equipment and devices such as the AV equipment, electric home applications, office machines and communications equipment, consequently, when employing these products for applications requiring a high degree of safety and reliability such as the medical equipment, aviation and aircraft equipment, space equipment and burglar alarm equipment, the using manufacturers will please thoroughly study the proprieties of these products for the planned applications.